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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-R5F
Core Size	32-Bit Single-Core
Speed	96MHz
Connectivity	CANbus, CSIO, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	116
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	88K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.25V
Data Converters	A/D 56x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP Exposed Pad
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6j311ahaase2000a

Pin No. S6J311xHAC	Pin Name	Polarity	I/O Circuit Type	Function
18	P020 SOT0_0 SDA0_0 TIOB1_0 TEXT1_0	- - - - -	P	General-purpose I/O port Multi-function serial ch.0 serial data output pin (0) I2C bus ch.0 serial data I/O pin Base timer ch.1 TIOB input pin (0) Free-run timer 1 clock input pin (0)
19	P021 SCK0_0 SCL0_0 TIOB2_0	- - - -	P	General-purpose I/O port Multi-function serial ch.0 clock I/O pin (0) I2C bus ch.0 serial clock I/O pin Base timer ch.2 TIOB input pin (0)
20	P022 SIN0_0 TIOB3_0 INT3_0	- - - -	P	General-purpose I/O port Multi-function serial ch.0 serial data input pin (0) Base timer ch.3 TIOB input pin (0) INT3 external interrupt input pin (0)
21	P023 SCS0_0 TIOB4_0	- - -	P	General-purpose I/O port Multi-function serial ch.0 serial chip select I/O pin (0) Base timer ch.4 TIOB input pin (0)
22	P024 TIOB5_0	- -	P	General-purpose I/O port Base timer ch.5 TIOB input pin (0)
23	P027 TIOA4_1 TIOB6_0 INT1_1 TEXT0_1	- - - - -	P	General-purpose I/O port Base timer ch.4 TIOA output pin (1) Base timer ch.6 TIOB input pin (0) INT1 external interrupt input pin (1) Free-run timer 0 clock input pin (1)
24	P028 SIN1_0 TIOB7_0 INT4_0 OUT0_1	- - - - -	P	General-purpose I/O port Multi-function serial ch.1 serial data input pin (0) Base timer ch.7 TIOB input pin (0) INT4 external interrupt input pin (0) Output compare ch.0 output pin (1)
25	P029 SOT1_0 SDA1_0 AN0 OUT1_1	- - - - -	A	General-purpose I/O port Multi-function serial ch.1 serial data output pin (0) I2C bus ch.1 serial data I/O pin ADC analog 0 input pin Output compare ch.1 output pin (1)
26	P030 OUT2_1	- -	P	General-purpose I/O port Output compare ch.2 output pin (1)
27	P031 SCS1_0 AN1 OUT3_1	- - - -	A	General-purpose I/O port Multi-function serial ch.1 serial chip select I/O pin (0) ADC analog 1 input pin Output compare ch.3 output pin (1)
28	P100 SCK1_0 SCL1_0 AN2 OUT4_1	- - - - -	A	General-purpose I/O port Multi-function serial ch.1 clock I/O pin (0) I2C bus ch.1 serial clock I/O pin ADC analog 2 input pin Output compare ch.4 output pin (1)
29	P101 AN3 OUT5_1	- - -	A	General-purpose I/O port ADC analog 3 input pin Output compare ch.5 output pin (1)
30	P103 AN5 OUT6_1	- - -	A	General-purpose I/O port ADC analog 5 input pin Output compare ch.6 output pin (1)
31	P105 TIOA9_0 OUT7_1	- - -	P	General-purpose I/O port Base timer ch.9 TIOA I/O pin (0) Output compare ch.7 output pin (1)
32	P106 OUT8_1	- -	P	General-purpose I/O port Output compare ch.8 output pin (1)
33	P107 TIOA10_0 INT2_1 OUT9_1	- - - -	P	General-purpose I/O port Base timer ch.10 TIOA output pin (0) INT2 external interrupt input pin (1) Output compare ch.9 output pin (1)

Pin No. S6J311xHAC	Pin Name	Polarity	I/O Circuit Type	Function
117	MD	-	C	Mode pin
118	X0	-	G	Main clock oscillation input pin
119	X1	-	G	Main clock oscillation output pin
121	P331	-	P	General-purpose I/O port
122	P400	-	P	General-purpose I/O port
123	RSTX	N	F	External reset input pin
127	P401 IN0_0	- -	Q	General-purpose I/O port Input capture ch.0 input pin (0)
128	P402 IN1_0 INT2_0	- - -	Q	General-purpose I/O port Input capture ch.1 input pin (0) INT2 external interrupt input pin (0)
129	P403 IN2_0 TRACEDATA0	- - -	Q	General-purpose I/O port Input capture ch.2 input pin (0) Trace data 0 output pin
130	P404 IN3_0 TRACEDATA1	- - -	Q	General-purpose I/O port Input capture ch.3 input pin (0) Trace data 1 output pin
131	P405 IN4_0 INT11_0 TRACEDATA2	- - - -	Q	General-purpose I/O port Input capture ch.4 input pin (0) INT11 external interrupt input pin (0) Trace data 2 output pin
132	P406 TRACEDATA3	- -	Q	General-purpose I/O port Trace data 3 output pin
133	P407 TRACEDATA4	- -	Q	General-purpose I/O port Trace data 4 output pin
134	P408 SIN2_0 INT12_0 TRACEDATA5	- - - -	Q	General-purpose I/O port Multi-function serial ch.2 serial data input pin (0) INT12 external interrupt input pin (0) Trace data 5 output pin
135	P409 SOT2_0 SDA2_0 TIOA24_1 TRACEDATA6	- - - - -	Q	General-purpose I/O port Multi-function serial ch.2 serial data output pin (0) I2C bus ch.2 serial data I/O pin Base timer ch.24 TIOA output pin (1) Trace data 6 output pin
136	P411 SCK2_0 SCL2_0 INT13_1 TRACEDATA7	- - - - -	Q	General-purpose I/O port Multi-function serial ch.2 clock I/O pin (0) I2C bus ch.2 serial clock I/O pin INT13 external interrupt input pin (1) Trace data 7 output pin
137	P413 SCS20_0 INT14_1	- - -	Q	General-purpose I/O port Multi-function serial ch.2 serial chip select 0 I/O pin (0) INT14 external interrupt input pin (1)
138	P414 SCS21_0	- -	Q	General-purpose I/O port Multi-function serial ch.2 serial chip select 1 output pin (0)
139	P416 IN5_0 TIOA22_1	- - -	Q	General-purpose I/O port Input capture ch.5 input pin (0) Base timer ch.22 TIOA output pin (1)
140	P417 TIOA23_1 INT15_1	- - -	Q	General-purpose I/O port Base timer ch.23 TIOA I/O pin (1) INT15 external interrupt input pin (1)
141	P418 SCS22_0 INT14_0	- - -	Q	General-purpose I/O port Multi-function serial ch.2 serial chip select 2 output pin (0) INT14 external interrupt input pin (0)

6. Handling Devices

For Latch-up Prevention

The latch-up phenomenon may occur on a CMOS IC in the following cases: the voltage applied to an input or output pin is higher than V_{CC} or lower than V_{SS} ; or the voltage applied between a V_{CC} pin and a V_{SS} pin exceeds the rating. A latch-up causes a rapid increase in the power supply current, possibly resulting in thermal damage to an element. When using the device, take sufficient care not to exceed the maximum rating.

Also be careful that analog power supplies ($AVCC0$, $AVCC1$, $AVRH0$, and $AVRH1$) and analog inputs do not exceed the digital power supply (V_{CC}) at the analog system power-on and power-off times.

The power-on sequence is as follows. Simultaneously turn on the digital supply voltage (V_{CC}) and analog supply voltages ($AVCC0$, $AVCC1$, $AVRH0$, and $AVRH1$), or turn on the digital supply voltage (V_{CC}) and then the analog supply voltages ($AVCC0$, $AVCC1$, $AVRH0$, and $AVRH1$).

About Handling Unused Pins

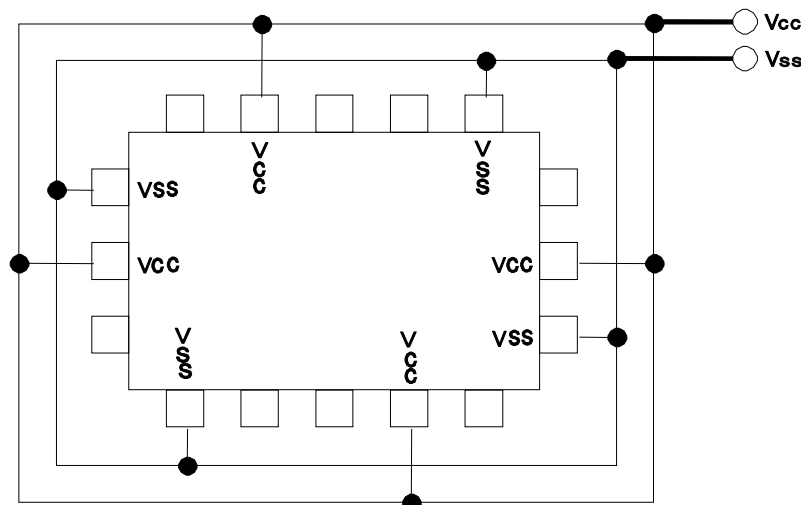
Leaving unused input pins open may cause permanent damage from a malfunction or latch-up. Take measures for unused pins, such as pulling up or pulling down the voltage with resistors of 2 kilohms or higher.

If there are any unused input/output pins, set them to the output state and then open them, or set them to the input state and handle them in the same way as input pins.

About Power Supply Pins

If the device has multiple V_{CC} and V_{SS} pins, the device is designed in such a way that the pins that should be at the same potential are connected to each other inside the device to prevent malfunctions such as latch-up. However, to reduce unwanted emissions, prevent malfunctions of strobe signals caused by an increase of the ground level, and observe standards on total output current, be sure to connect all the V_{CC} and V_{SS} pins to the power source and ground externally. Also handle all the V_{SS} power supply pins in this way as shown in the following diagram. If there are multiple V_{CC} or V_{SS} systems, the device does not operate normally even within the guaranteed operating range.

Figure 6-1. Pin Assignment



In addition, consider connecting with low impedance from the power supply source to the V_{CC} and V_{SS} of this device.

In the area close to this device, a ceramic capacitor having the capacitance larger than the capacitor of C pin is recommended to use as a bypass capacitor between the V_{CC} pin and the V_{SS} pin.

About the Crystal Oscillation Circuit

Noise entering the X0 or X1 pin may cause a malfunction. Design the printed circuit board in such a way that the X0 and X1 pins, the crystal oscillator (or ceramic resonator), and a bypass capacitor to ground are located very close to the device.

We recommend that the printed circuit board artwork have the X0 and X1 pins enclosed by ground.

9. Pin Status in CPU Status

Table 9-1. Pin State Table (1/2)

Pin No.	Pin Name	GPORTEN Control	External Reset Factor 1			External Reset Factor 2				External Reset Factor 3		Internal Reset Factor *2	Sleep mode	Stop mode *4		Timer mode *4	
			External factor generation in progress		After external factor releasing	While Generating External Factor		After Releasing External Factor		External Reset Factor 3				High impedance disabled (SYSC0_SPECFGR, PSSPACTRL=0)	High impedance enabled (SYSC0_SPECFGR, PSSPACTRL=1)	High impedance disabled (SYSC0_SPECFGR, PSSPACTRL=0)	High impedance enabled (SYSC0_SPECFGR, PSSPACTRL=1)
			Internal reset issuance in progress	Internal reset issuance in progress		Before internal reset issuance	Internal reset issuance in progress	Internal reset issuance in progress	After internal reset issuance (Before GPORT setting)	Internal reset issuance in progress	After internal reset (Before GPORT setting)						
2	P000/SOT2_1	With control	Hi-Z/ Input blocked	Hi-Z/ Last status retained	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Status immediately before the shutdown retains	Last state retained	Last state retained (*3)	Last state retained (*3)	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Last state retained (*3)	Hi-Z/ Input blocked	
3	P001/SCS20_1																
4	P003/SCS22_1																
5	P005/IN6_0/SIN0_0																
6	P006/SOT3_0/SDA3_0/INT7_0																
7	P007/SCK3_0/SC13_0/IN8_0																
8	P008/IN9_0/SCS30_0/TIOA0_0																
9	P009/IN10_0/TIOA1_0/INT0_1																
10	P010/IN11_0/TIOA2_0																
11	P012/OUT5_0/TIOA3_0																
12	P013/OUT6_0/TIOA4_0																
13	P015/OUT7_0/TIOA5_0																
14	P016/OUT8_0/TIOA6_0																
15	P017/OUT9_0/TIOA7_0																
16	P018/OUT10_0/TIOA8_0																
17	P019/OUT11_0/TIOB0_0/TEXT0_0																
18	P020/SOT0_0/SDA0_0/TEXT1_0/TIOB1_0																
19	P021/SCK0_0/SC10_0/TIOB2_0																
20	P022/SIN0_0/TIOB3_0/INT3_0																
21	P023/SCS0_0/TIOB4_0																
22	P024/TIOB5_0																
23	P027/TIOA4_1/TIOB6_0/INT1_1/TEXT0_1																
24	P028/OUT0_1/SIN1_0/TIOB7_0/INT4_0																
25	P029/AN0/SOT1_0/SDA1_0/OUT1_1																
26	P030/OUT2_1																
27	P031/OUT3_1/SCS1_0/AN1																
28	P100/AN2/SCK1_0/SC11_0/OUT4_1																
29	P101/OUT5_1/AN3																
30	P103/OUT6_1/AN5																
31	P105/OUT7_1/TIOA9_0																
32	P106/OUT8_1																
33	P107/OUT9_1/TIOA10_0/INT2_1																
34	P108/OUT10_1/AN6/TIOA11_0/INT3_1																
35	P109/OUT11_1/TIOA12_0																
39	P112/AN9/TIOA13_0																
40	P113/TIOA5_1																
41	P114/AN10/TIOA6_1																
45	P115																
46	P117/AN12/INT4_1																
47	P118/AN13/INT5_1																
48	P119/AN14																
49	P120/AN15																
50	P122/AN17/TIOA11_1																
51	P123/AN18/TIOA12_1																
52	P126/AN19																
53	P127/AN20/TEXT1_1																
54	P128/AN21/TEXT2_1																
55	P129/IN6_1/AN22																
56	P130/IN7_1/AN23/INT5_0																
57	P131/IN8_1/AN24																
58	P202/IN0_1/INT6_1																
59	P203/IN10_1																
60	P204/IN11_1/AN27																
61	P205/AN28/TEXT3_1																
62	P206/AN29/TEXT4_1																
63	P207/AN30/INT7_1/TEXT5_1																
64	P208/AN31/TIOA19_0																
65	P209/AN32/TIOA20_0																
66	P210/IN0_2/AN33/TIOA21_0/INT6_0																
67	P211/IN1_2/AN34/TIOA22_0																
68	P212/IN2_2/AN35/TIOA13_1																
69	P213/IN3_2/TIOA14_1/INT8_1																
70	P214/IN4_2/TIOA15_1																
71	P215/IN5_2/TIOA16_1/INT9_1																

Table 9-2. Pin State Table (2/2)

Pin No.	Pin Name	GPORTEN Control	External Reset Factor 1			External Reset Factor 2			External Reset Factor 3	Internal Reset Factor 2	Sleep mode	Stop mode *4		Timer mode *4	
			External factor generation in progress	After external factor releasing	While Generating External Factor	After Releasing External Factor	External Reset Factor 3	High impedance disabled (SYSIO_SPCFG_PSSPACTRL=0)				High impedance enabled (SYSIO_SPCFG_PSSPACTRL=1)	High impedance disabled (SYSIO_SPCFG_PSSPACTRL=0)	High impedance enabled (SYSIO_SPCFG_PSSPACTRL=1)	
															Internal reset issuance in progress
74	P218/AN36/TEXT2_0	With control	Hi-Z/ Input blocked	Hi-Z/ Last status retained	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Status immediately before the shutdown retain	Last state retained	Last state retained (*3)	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Last state retained (*3)	Hi-Z/ Input blocked
75	P219/AN37/TEXT3_0														
76	P220/IN6_2/AN38														
77	P222/INT_2/AN39/INT7_0														
78	P223/IN8_2/AN40/PWU_AN0														
79	P224/IN9_2/TX0_2/AN41/PWU_AN1														
80	P225/IN10_2/RX0_2/AN42/INT0_0/PWU_AN2														
81	P226/IN11_2/AN43/TIOA17_1/PWU_AN3														
85	P227/AN44/TIOA23_0/PWU_AN4														
86	P228/TX0_1/AN45/TIOA24_0/PWU_AN5														
87	P229/OUT0_0/RX0_1/AN46/TIOA25_0/INT8_0/PWU_AN6														
88	P230/OUT1_0/AN47/TIOA26_0/PWU_AN7														
89	P231/OUT2_0/AN49/TIOA27_0														
90	P300/OUT3_0/AN49/TIOA28_0														
91	P301/OUT4_0/AN50/TIOA18_1														
92	P302/AN51/TIOA19_1														
93	P304/AN52/TIOA20_1/TEXT4_0														
94	P305/AN53/TIOA29_0/TEXT5_0														
95	NMIX	-	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	
96	P306/TX0_0/AN54	With control	Hi-Z/ Input blocked	Hi-Z/ Last status retained	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Status immediately before the shutdown retain	Last state retained	Last state retained (*3)	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Last state retained (*3)	Hi-Z/ Input blocked
97	P307/RX0_0/AN55/INT1_0														
98	P308/IN0_1/AN56/TIOA28_1														
99	P309/IN1_1/AN57/TIOA29_1														
100	P312/IN2_1/AN58														
101	P313/IN3_1/AN59/INT10_1														
102	P314/IN4_1/AN60/TIOA7_1														
103	P315/IN5_1/AN61/TIOA8_1														
104	P317/AN62/TIOA9_1/INT11_1														
107	P321/PWUTRG	With control	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked *7 (Status immediately before the shutdown retain) *6 (PWUTRG output/Input blocked *5)	Hi-Z/ Input blocked *7 (Last state retained) *6 (PWUTRG output/Input blocked *5)	Hi-Z/ Input blocked *7 (Last state retained) *6 (PWUTRG output/Input blocked *5)	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked *7 (Last state retained) *3 *6 (*5)	Hi-Z/ Input blocked	
110	TRSTP322														
111	TDOIP323														
112	TDVP324														
113	TMS														
114	TCK														
115	P327														
116	P330														
117	MD														
118	XD														
119	XI														
121	P331	With control	Hi-Z/ Input blocked	Hi-Z/ Last status retained	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Status immediately before the shutdown retain	Last state retained	Last state retained (*3)	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Last state retained (*3)	Hi-Z/ Input blocked
122	P400														
123	RSTX														
127	P401/IN0_0														
128	P402/IN1_0/INT2_0														
129	P403/IN2_0/TRACEDATA0														
130	P404/IN3_0/TRACEDATA1														
131	P405/IN4_0/INT11_0/TRACEDATA2														
132	P406/TRACEDATA3														
133	P407/TRACEDATA4														
134	P408/SIN2_0/INT12_0/TRACEDATA5	With control	Hi-Z/ Input blocked	Hi-Z/ Last status retained	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Status immediately before the shutdown retain	Last state retained	Last state retained (*3)	Hi-Z/ Input blocked	Hi-Z/ Input blocked	Last state retained (*3)	Hi-Z/ Input blocked
135	P409/SOT2_0/SDA2_0/TIOA24_1/TRACEDATA6														
136	P411/INT13_1/SCK2_0/ISCL2_0/TRACEDATA7														
137	P413/SCS20_0/INT14_1														
138	P414/SCS21_0														
139	P416/IN5_0/TIOA22_1														
140	P417/TIOA23_1/INT15_1														
141	P418/SCS22_0/INT14_0														
142	P420/SCK2_1/TRACECLK														
143	P422/SIN2_1/TRACECTL														

Notes:

- The following condition should be satisfied in order to facilitate heat dissipation.
 1. 4 or more layers PCB should be used.
 2. The area of PCB should be 114.3 mm x 76.2 mm or more, and the thickness should be 1.6 mm or more. (JEDEC standard)
 3. 1 layer of middle layers at least should be used for dedicated layer to radiate heat with residual copper rate 90% or more. The layer can be used for system ground.
 4. 35~50% of the die stage area which is exposed at back surface of package should be soldered to a part of 1st layer.
 5. The part of 1st layer should be connected to the dedicated heat radiation layer with more than 10 thermal via holes.

Figure10.2-1: Example thermal via holes on PCB.


Notes:

- Figure 10.2-1 is a schematic diagram showing PCB in section.
- Figure 10.2-2 in the following pages are recommended land patterns for each package series. Thermal via holes should closely be placed and aligned with lands.
- If you are considering application under any conditions other than listed herein, please contact sales representatives beforehand.

10.4 AC Characteristics

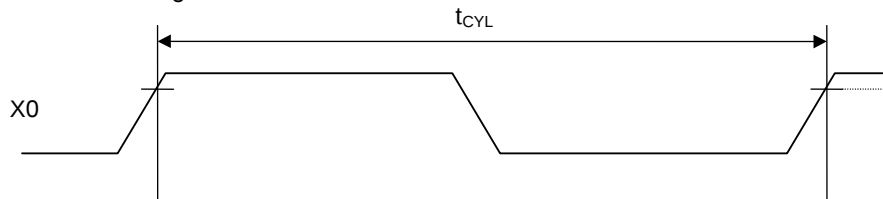
10.4.1 Source Clock Timing

(T_A: Recommended operating conditions, V_{CC}=5.0 V +5%/-10%, V_{SS}=AV_{SS}=0.0 V)

Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Source oscillation clock frequency	F _C	X0, X1	-	-	4	-	MHz	
Source oscillation clock cycle time	t _{CYL}	X0, X1	-	-	250	-	ns	
CAN PLL jitter (during lock)	t _{PJ}	-	-	-10	-	+10	ns	*
Built-in slow-CR oscillation frequency	F _{CRS}	-	-	50	100	150	kHz	
Built-in fast-CR oscillation frequency	F _{CRF}	-	-	2.4	4	6.0	MHz	
PLL input clock frequency	F _{PLLI}	-	-	-	4	-	MHz	
PLL macro oscillation clock frequency	F _{PLLO}	-	-	400	-	576	MHz	
SSCG-PLL input clock frequency	F _{SSCGPLLI}	-	-	-	4	-	MHz	
SSCG-PLL macro oscillation clock frequency	F _{SSCGPLLO}	-	-	400	-	576	MHz	

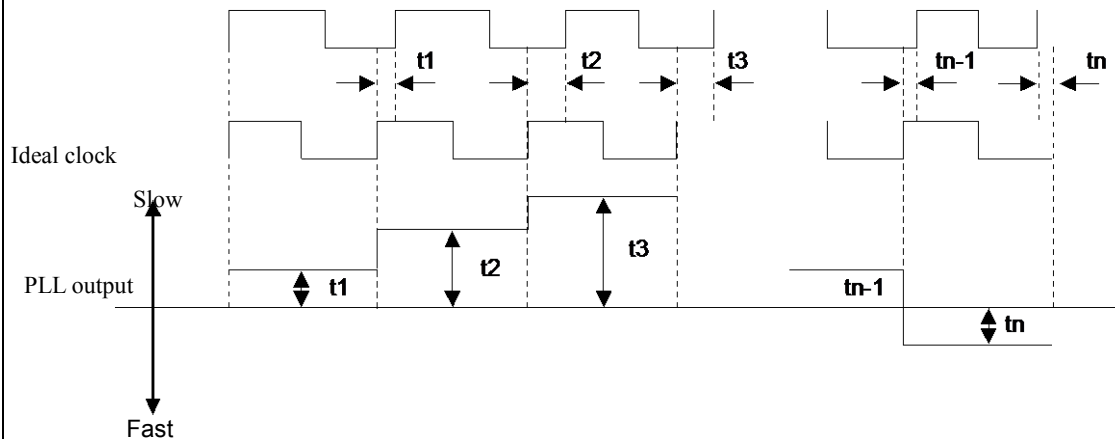
* The maximum/minimum values have been standardized with the main clock and PLL clock in use.

• X0 and X1 clock timing



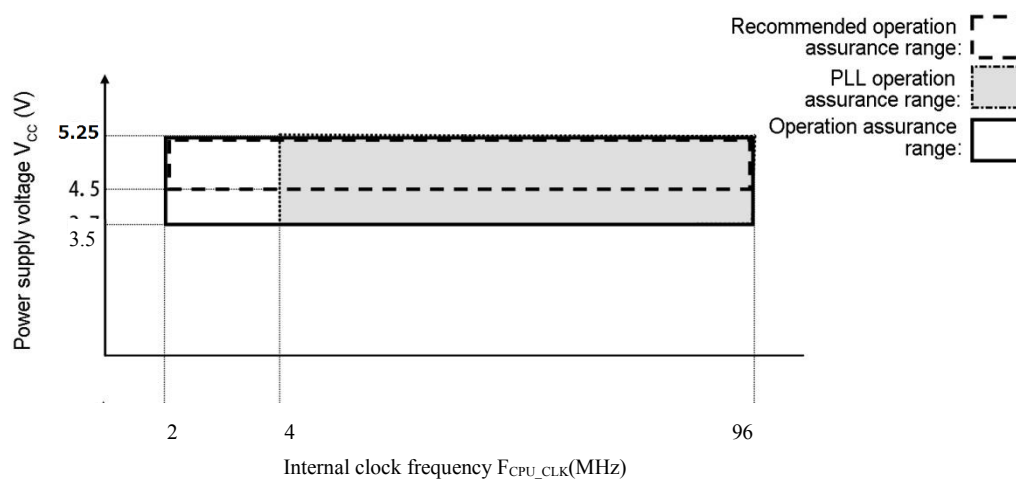
• CAN PLL jitter

A time difference from the ideal clock is guaranteed for each cycle period within 20,000 cycles.

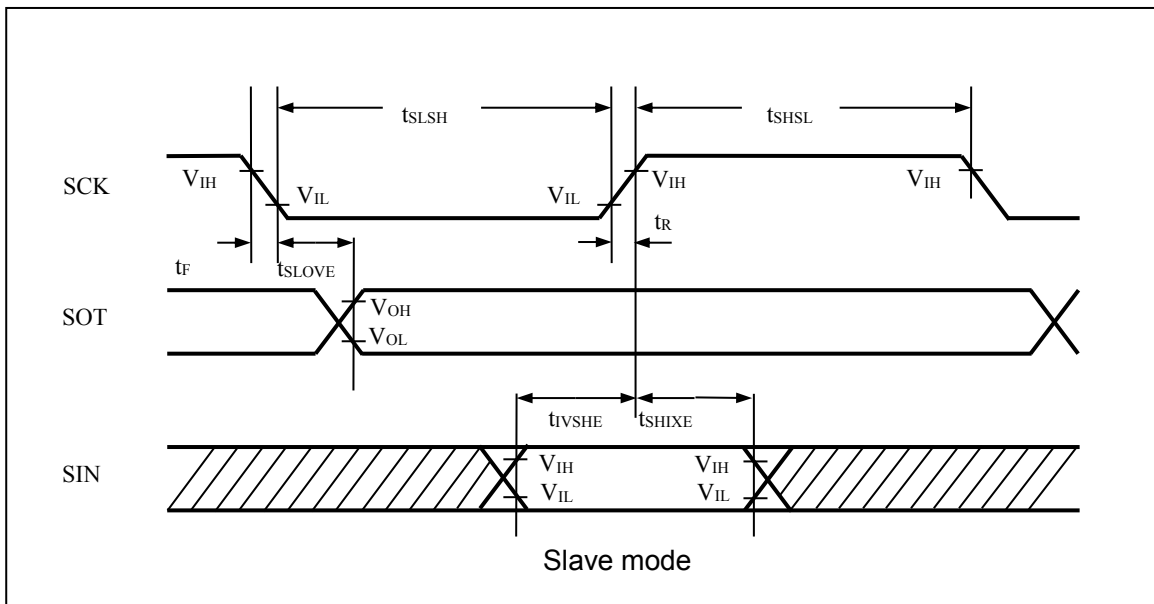
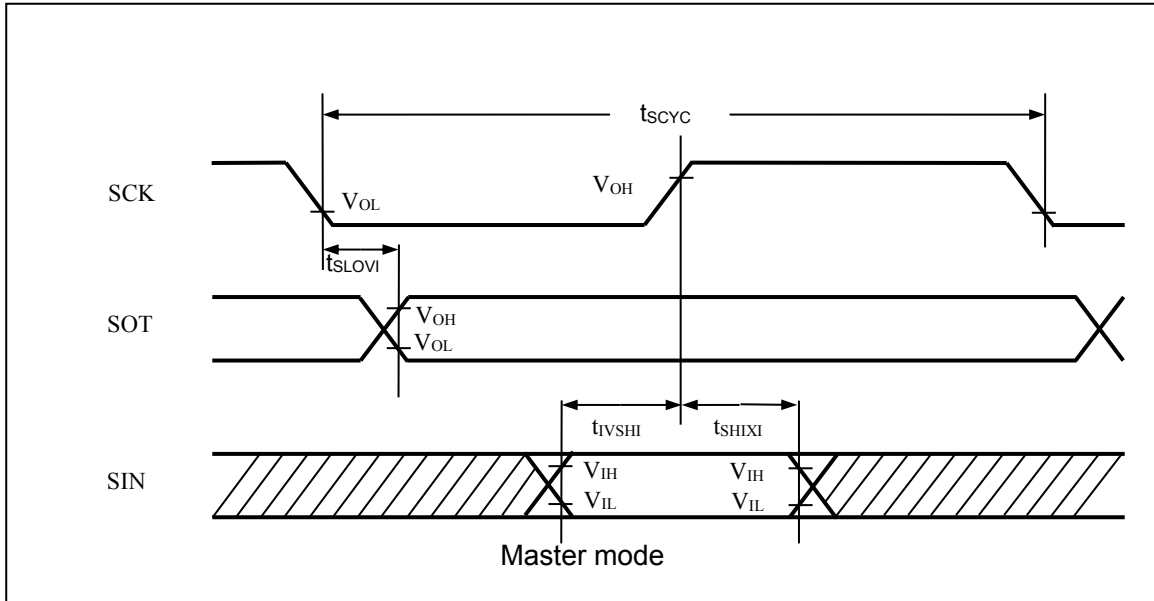


Parameter	Symbol	Pin Name	Conditions	S6J311xHAC* Value * x:A/9			Unit	Remarks
				Min	Typ	Max		
t_{CLK_LCP0A}	-	-	-	41.6	-	-	ns	CLK_LCP0A
t_{CLK_LCP1}	-	-	-	41.6	-	-	ns	CLK_LCP1
t_{CLK_LCP1A}	-	-	-	41.6	-	-	ns	CLK_LCP1A
t_{CLK_LAPP0}	-	-	-	41.6	-	-	ns	CLK_LAPP0
t_{CLK_LAPP0A}	-	-	-	41.6	-	-	ns	CLK_LAPP0A
t_{CLK_LAPP1}	-	-	-	41.6	-	-	ns	CLK_LAPP1
t_{CLK_LAPP1A}	-	-	-	41.6	-	-	ns	CLK_LAPP1A
t_{CLK_TRC}	-	-	-	20.8	-	-	ns	CLK_TRC
t_{CLK_HSSPI}	-	-	-	41.6	-	-	ns	CLK_HSSPI
t_{CLK_SYSC0H}	-	-	-	41.6	-	-	ns	CLK_SYSC0H
t_{CLK_COMH}	-	-	-	41.6	-	-	ns	CLK_COMH
t_{CLK_RAM0H}	-	-	-	41.6	-	-	ns	CLK_RAM0H
t_{CLK_RAM1H}	-	-	-	41.6	-	-	ns	CLK_RAM1H
t_{CLK_SYSC0P}	-	-	-	41.6	-	-	ns	CLK_SYSC0P
t_{CLK_COMP}	-	-	-	41.6	-	-	ns	CLK_COMP
t_{CANFD_CCLK}	-	-	-	25.0	-	-	ns	CANFD_CCLK

• Guaranteed operation range
 Internal operation clock frequency vs. Power supply voltage



Note: A supply voltage that is equal to or less than the set voltage for low-voltage detection causes a reset.



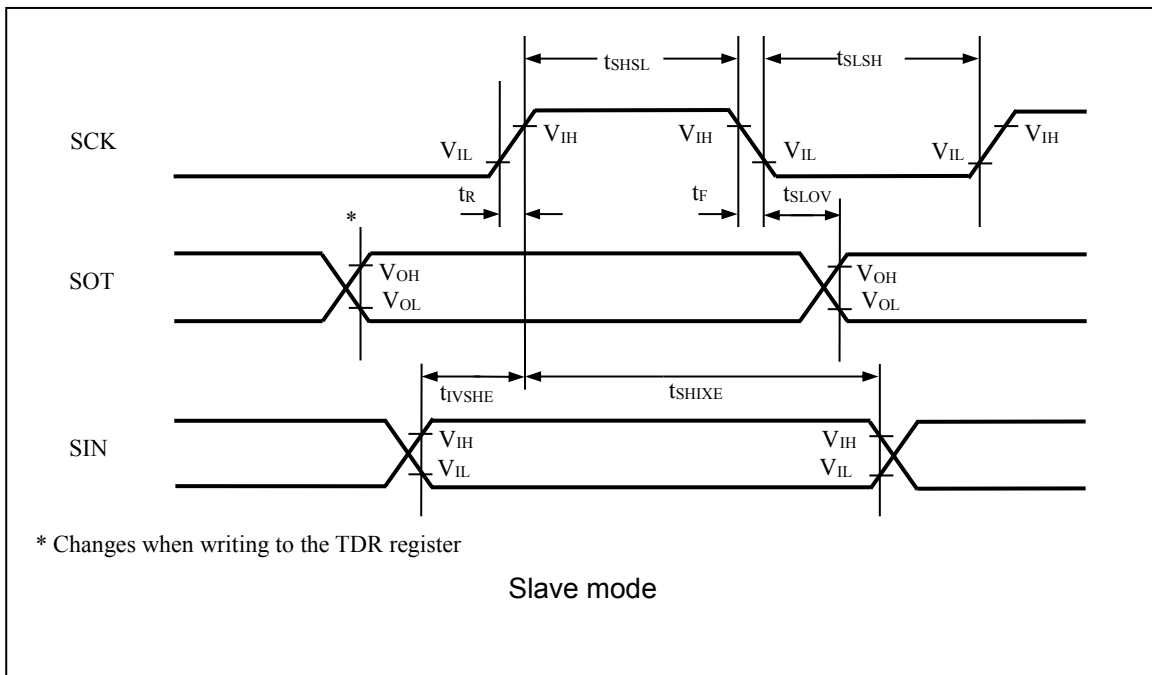
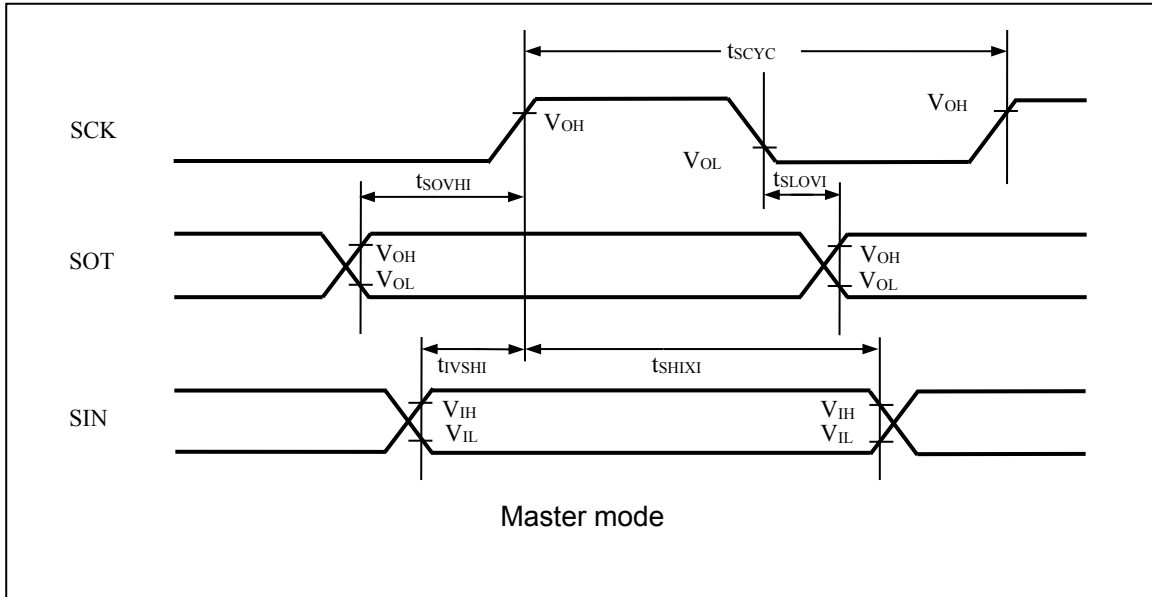
(5-1-4) SPI Supported (SCR:SPI=1), and Serial Clock Output Signal Detect Level "L" (SMR:SCINV=1)

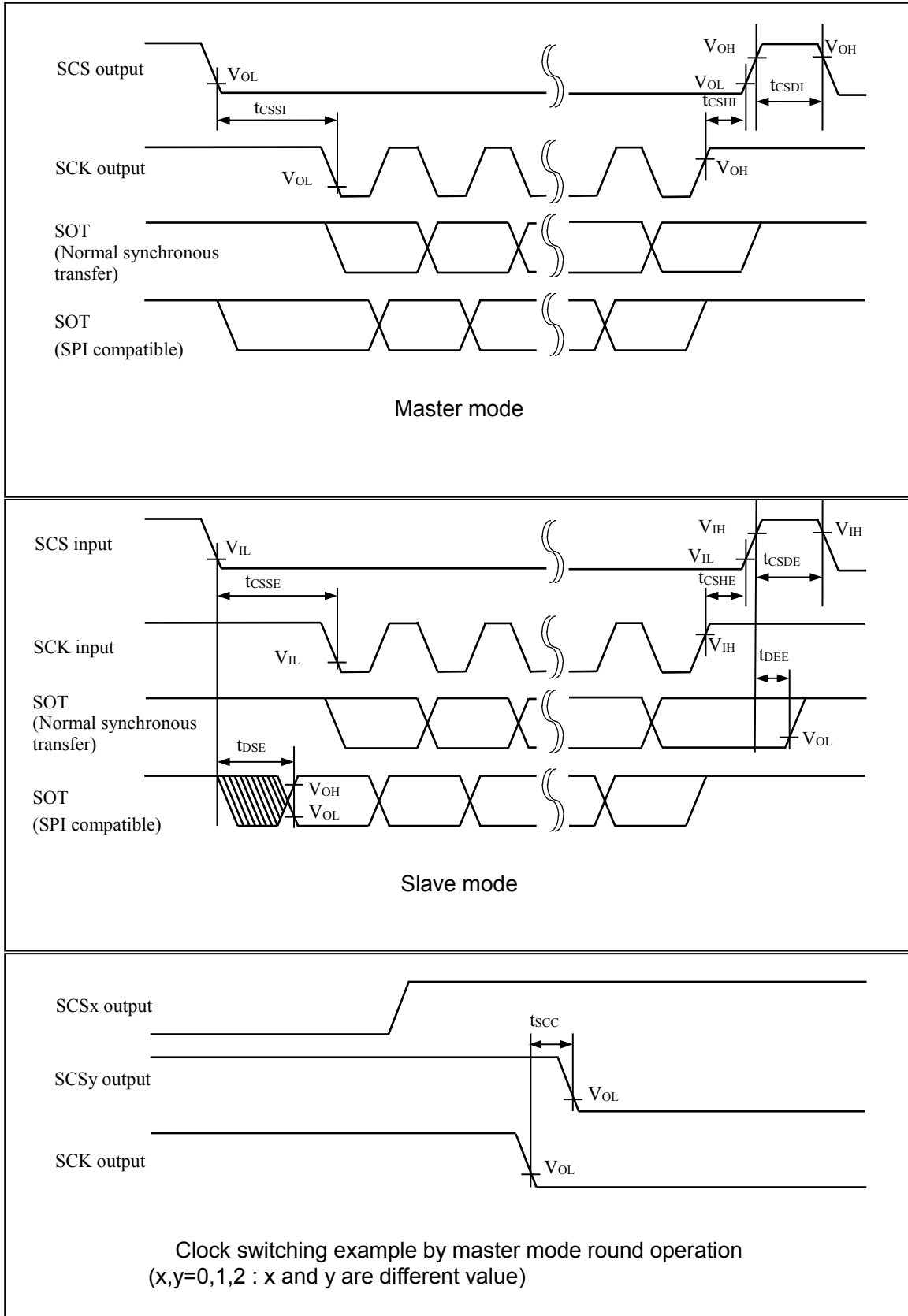
 (TA: Recommended operating conditions, V_{CC}=5.0 V +5%/-10%, V_{SS}=AV_{SS}=0.0 V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Serial clock cycle time	t _{SCYC}	SCK0 to SCK3	Master mode (CL=50pF, I _{OL} =-2mA, I _{OH} =2mA), (CL=20pF, I _{OL} =-1mA, I _{OH} =1mA)	4t _{CLK_LCP0A}	-	ns	
SCK ↓ → SOT delay time	t _{SLOVI}	SCK0 to SCK3, SOT0 to SOT3		-30	+30	ns	
Valid SIN → SCK ↑ setup time	t _{IVSHI}	SCK0 to SCK3, SIN0 to SIN3		30	-	ns	
SCK ↑→ Valid SIN hold time	t _{SHIXI}			0	-	ns	
SOT → SCK ↑ delay time	t _{SOVHI}	SCK0 to SCK3, SOT0 to SOT3		2t _{CLK_LCP0A} -30	-	ns	
Serial clock "H" pulse width	t _{SHSL}	SCK0 to SCK3	Slave mode (CL=50pF, I _{OL} =-2mA, I _{OH} =2mA), (CL=20pF, I _{OL} =-1mA, I _{OH} =1mA)	t _{CLK_LCP0A} +10	-	ns	
Serial clock "L" pulse width	t _{SLSH}			2t _{CLK_LCP0A} -10	-	ns	
SCK ↓ → SOT delay time	t _{SLOVE}	SCK0 to SCK3, SOT0 to SOT3		-	45	ns	
Valid SIN → SCK ↑ setup time	t _{IVSHE}	SCK0 to SCK3, SIN0 to SIN3		10	-	ns	
SCK ↑ → Valid SIN hold time	t _{SHIXE}			20	-	ns	
SCK fall time	t _F	SCK0 to SCK3		-	5	ns	
SCK rise time	t _R	SCK0 to SCK3		-	5	ns	

Notes:

- This is the AC characteristic in CLK synchronized mode.
- CL is the load capacitance applied to pins during testing.
- The maximum baud rate is limited by the internal operating clock used and other parameters.
For details, see the hardware manual.





(5-1-6) Serial Chip Select Used (SCSCR:CSEN=1)

■ Serial clock output signal detect level "L" (SMR, SCSFR:SCINV=1)

■ Serial chip select inactive level "H" (SCSCR, SCSFR:CSLVL=1)

(TA: Recommended operating conditions, V_{CC}=5.0 V +5%/-10%, V_{SS}=AV_{SS}=0.0 V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
SCS ↓ → SCK ↑ setup time	t _{CSSU}	SCK0 to SCK3, SCS0x to SCS3x	Master mode (CL=50pF, I _{OL} =-2mA, I _{OH} =2mA), (CL=20pF, I _{OL} =-1mA, I _{OH} =1mA)	t _{CSSU} ^{*1} -50	-	ns	
SCK ↓ → SCS ↑ hold time	t _{CSDH}			t _{CSDH} ^{*2} +0	-	ns	
SCS deselect time	t _{CSDI}			SCS0x to SCS3x	t _{CSDS} ^{*3} -50+5 t _{CLK_LCP0A}	-	
SCS ↓ → SCK ↑ setup time	t _{CSSE}	SCK0 to SCK3, SCS0x to SCS3x	Slave mode (CL=50pF, I _{OL} =-2mA, I _{OH} =2mA), (CL=20pF, I _{OL} =-1mA, I _{OH} =1mA)	3t _{CLK_LCP0A} +30	-	ns	
SCK ↓ → SCS ↑ hold time	t _{CSHE}			0	-	ns	
SCS deselect time	t _{CSDE}	SCS0x to SCS3x		3t _{CLK_LCP0A} +30	-	ns	
SCS ↓ → SOT delay time	t _{DSE}	SCS0x to SCS3x, SOT0 to SOT3		-	50	ns	
SCS ↑ → SOT delay time	t _{DEE}			0	-	ns	
SCK ↑ → SCS ↓ clock switching time	t _{SCC}	SCK0 to SCK3, SCS0x to SCS3x	Master mode round operation (CL=50pF, I _{OL} =-2mA, I _{OH} =2mA), (CL=20pF, I _{OL} =-1mA, I _{OH} =1mA)	3t _{CLK_LCP0A} +0	3t _{CLK_LCP0A} +50	ns	

*1: t_{CSSU}=SCSTR:CSSU[7:0] x serial chip select timing operating clock

*2: t_{CSDH}=SCSTR:CSHD[7:0] x serial chip select timing operating clock

*3: t_{CSDS}=SCSTR:CSDS[15:0] x serial chip select timing operating clock

For details on *1, *2, and *3 above, see the hardware manual.

Notes:

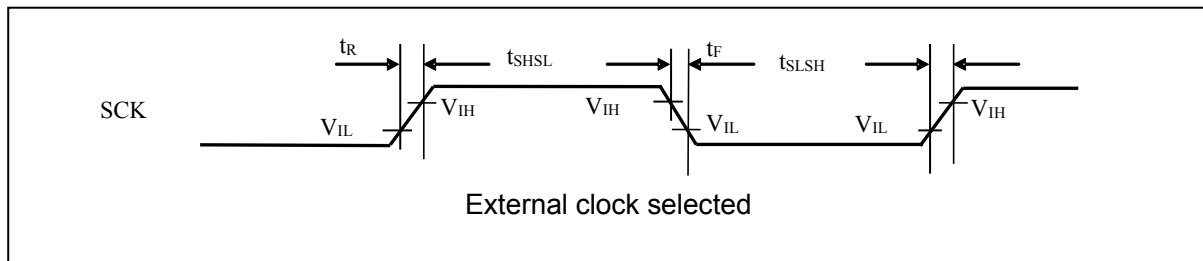
- This is the AC characteristic in CLK synchronized mode.
- CL is the load capacitance applied to pins during testing.
- The maximum baud rate is limited by the internal operating clock used and other parameters.
For details, see the hardware manual.

10.4.5.3 LIN Interface (v2.1) (LIN Communication Control Interface (v2.1)) Timing (SMR:MD[2:0]=011_B)

(5-3-1) External Clock Selected (BGR:EXT=1)

(T_A: Recommended operating conditions, V_{CC}=5.0 V +5%/-10%, V_{SS}=AV_{SS}=0.0 V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Serial clock "L" pulse width	t _{SLSH}	SCK0 to SCK3	(CL=50pF, I _{OL} =-2mA, I _{OH} =2mA), (CL=20pF, I _{OL} =-1mA, I _{OH} =1mA)	t _{CLK_LCP0A} +10	-	ns	
Serial clock "H" pulse width	t _{SHSL}			t _{CLK_LCP0A} +10	-	ns	
SCK fall time	t _F			-	5	ns	
SCK rise time	t _R			-	5	ns	



10.4.5.4 I²C timing (SMR:MD[2:0]=100B)

(T_A: Recommended operating conditions, V_{CC}=5.0 V +5%/-10%, V_{SS}=AV_{SS}=0.0 V)

Parameter	Symbol	Pin Name	Conditions	Standard Mode		Unit	Remarks
				Min	Max		
SCL clock frequency	f _{SCL}	SCL0 to SCL3	C _L =50pF, R=(V _p /I _{OL}) ^{*1}	0	100	kHz	
Repeat "start" condition hold time SDA ↓ → SCL ↓	t _{HDESTA}	SDA0 to SDA3 SCL0 to SCL3		4.0	-	μs	
Period of "L" for SCL clock	t _{LOW}	SCL0 to SCL3		4.7	-	μs	
Period of "H" for SCL clock	t _{HIGH}			4.0	-	μs	
Repeat "start" condition setup time SCL ↑ → SDA ↓	t _{SUSTA}	SDA0 to SDA3 SCL0 to SCL3		4.7	-	μs	
Data hold time SCL ↓ → SDA ↓ ↑	t _{HDDAT}			0	3.45 ^{*2}	μs	
Data setup time SDA ↓ ↑ → SCL ↑	t _{SUDAT}			250	-	ns	
"Stop" condition setup time SCL ↑ → SDA ↑	t _{SUSTO}			4.0	-	μs	
Bus-free time between "stop" condition and "start" condition	t _{BUF}	-		4.7	-	μs	
Noise filter	t _{SP}	-		t _{NFT} ^{*3}	-	ns	

*1: R and CL represent the pull-up resistance and load capacitance of the SCL and SDA output lines, respectively V_p shows that the power-supply voltage of the pull-up resistor and I_{OL} shows the VOL guarantee current.

*2: The maximum t_{HDDAT} only has to be met if the device does not extend the "L" width (t_{LOW}) of the SCL signal.

*3: t_{NFT}=(NFCR:NFT[4:0]+1) x 2 x tCLK_LCP0A

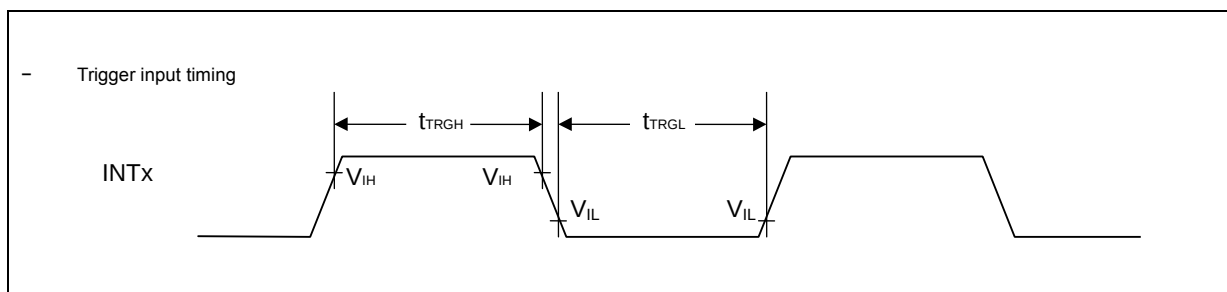
Notes:

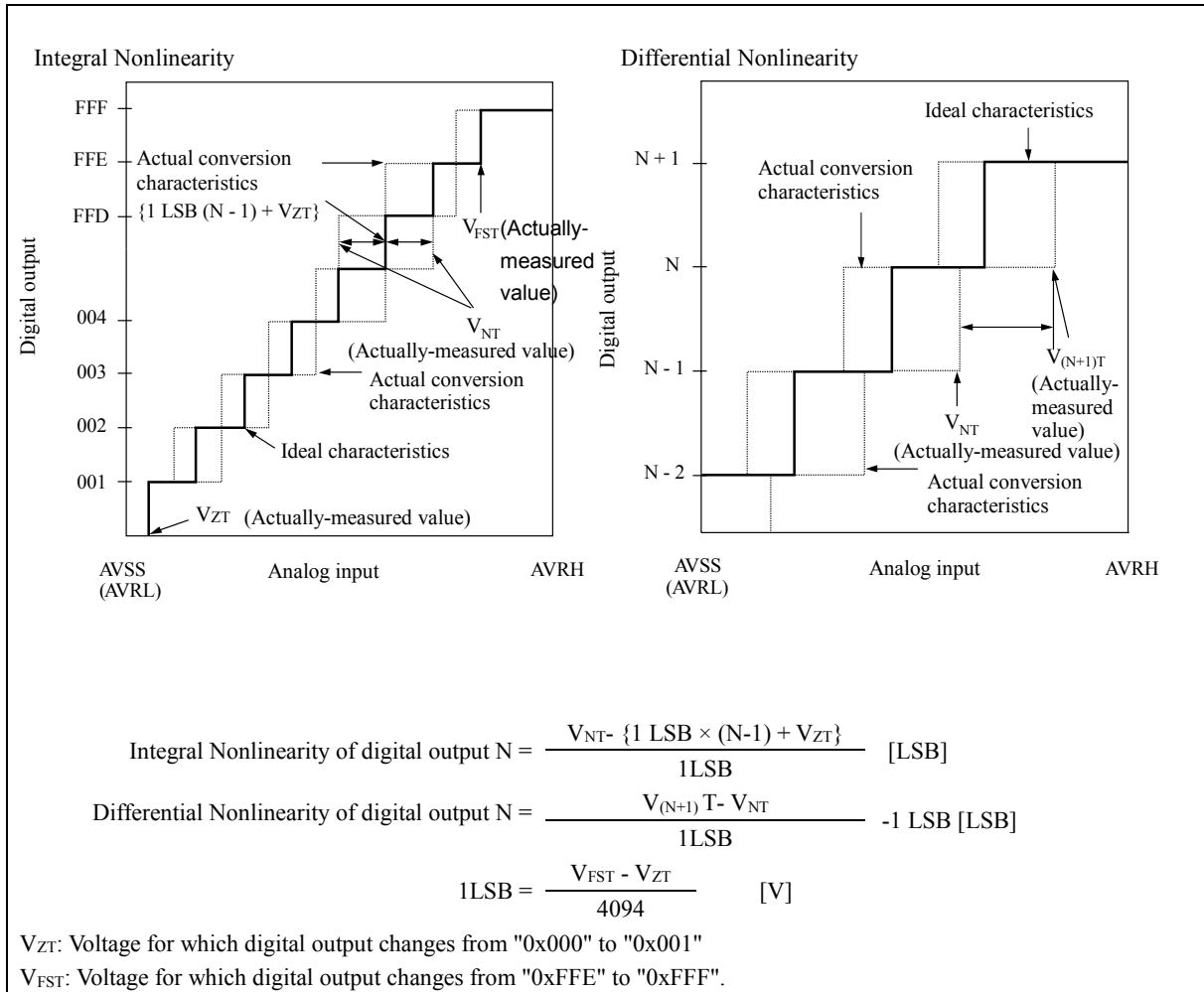
- In this device, Standard mode (Max. 100kbps) is supported only.
- This model does not support high-speed mode. (Max. 400kbps).
- This model does not support Min. I_{OL} = 3mA with V_{OL} = 0.4V.

10.6 Trigger Input Timing

(T_A: Recommended operating conditions, V_{CC}=5.0 V +5%/-10%, V_{SS}=AV_{SS}=0.0 V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t _{TRGH} , t _{TRGL}	INT0 to INT15	-	100	-	ns	
		INT0 to INT15	-	1	-	μs	Stop mode





11. Ordering Information

Part Number	Package
S6J311xHzCSEy0000	144-pin Plastic TEQFP (LEU144)

Note:

- "x"/"y" is a part number option. For the part number option, see the following table.
For details on each package, see "PACKAGE DIMENSIONS."
- * z: A

12. Part Number Option

Part Number Option "x"	FLASH Memory
A	1MByte
9	768KByte

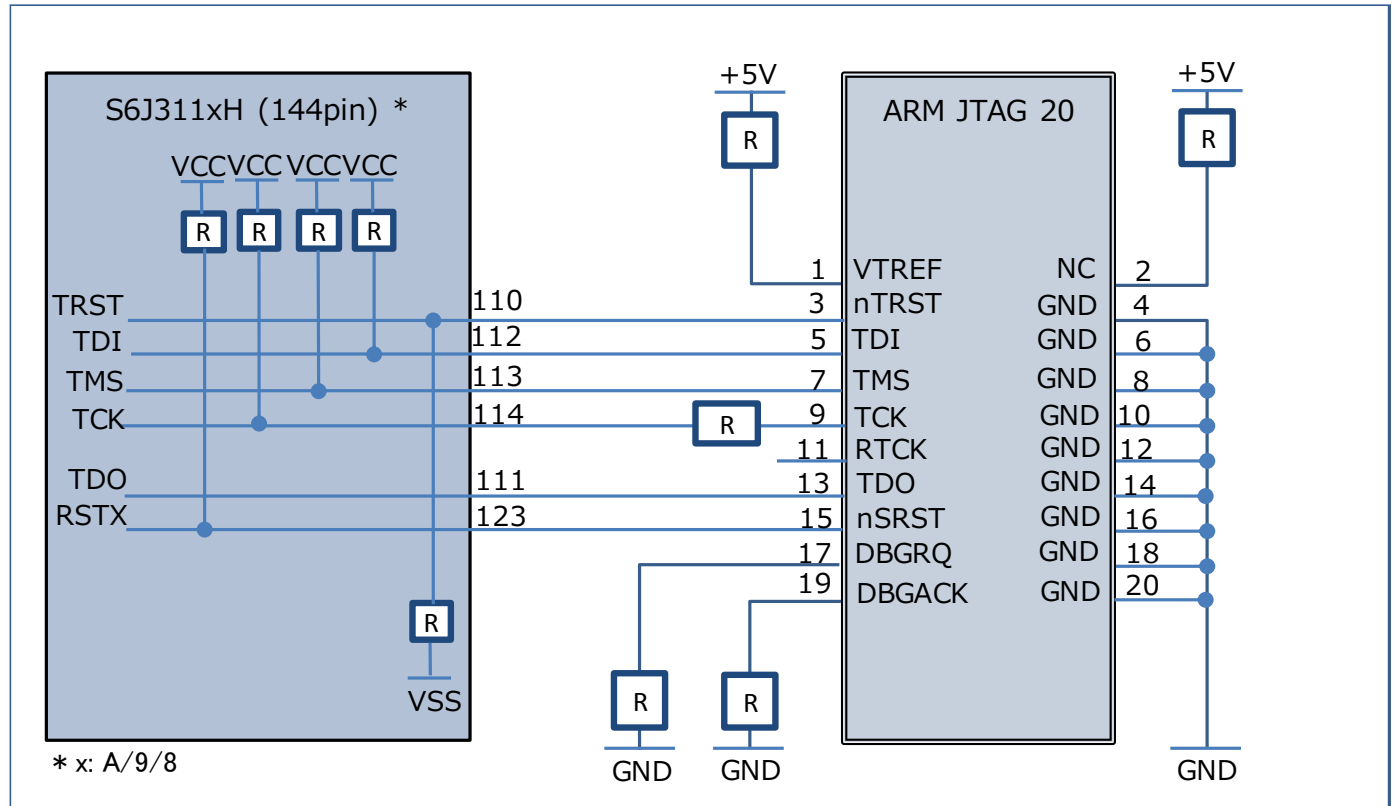
Part Number Option "y"	
2	PureSn & Halogen Free

Part Number Option "z"	SHE
A	SHE ON

14. Appendix

14.1 Application 1: JTAG tool connection

This is an application example of JTAG tool connection. See the relevant application note AN203911 in detail.



15. Major Changes

Spanision Publication Number: S6J311A_DS708-00004

Page	Section	Change Results
Revision 0.1		
-	-	Initial release
Revision 1.0		
1,3	Cover	Added the family product names(S6J3119HAA / S6J3118HAA)
1,3	Cover	Revised the level of this data sheet as full production
6	2. Features 2.2 Peripheral Functions	Added the information about the memory capacity expansion
7	2. Features 2.2 Peripheral Functions	Revised the CAN transfer speed to 5Mbps
9	3. Product Lineup	Added the specifications as full production
11	4. Pin Assignment	Revised the product names of title S6J311AHAA-> S6J311xHAA
12	5. Pin Description	Revised the product names of title S6J311AHAA-> S6J311xHAA
12~21	5. Pin Description	Revised the product names of Pin No. S6J311AHAA-> S6J311xHAA
30	8. Handling Devices	Revised the note of "About power supply pins"
32	8. Handling Devices	Revised the note of "About C pin processing"(Delete "and pin 38")
33	9. Block Diagram	Revised the block diagram of S6J311xHAA as full production
34	10. Memory Map	Revised the memory map of S6J311xHAA (added information of S6J3119HAA / S6J3118HAA)
36	10.Memory Map	Revised the product names of title S6J311AHAA-> S6J311xHAA
42,44,52,55	12. Electrical Characteristics	Added the product names S6J311AHAA-> S6J311xHAA
42	12. Electrical Characteristics 12.1 Absolute Maximum Ratings	Revised "Remarks" of Analog supply voltage to "AV _{CC} =V _{CC} "
42	12. Electrical Characteristics 12.1 Absolute Maximum Ratings	Revised the note of *2
42	12. Electrical Characteristics 12.1 Absolute Maximum Ratings	Revised the symbol of Maximum clamp current
43	12. Electrical Characteristics 12.1 Absolute Maximum Ratings	Moved the note of *8 to the bottom of note
44	12. Electrical Characteristics 12.2 Recommended Operating Conditions	Delete the information about CS2
44	12. Electrical Characteristics 12.2 Recommended Operating Conditions	Revised C pin connection diagram
44	12. Electrical Characteristics 12.2 Recommended Operating Conditions	Added "Remarks" of Smoothing capacitor
45	12. Electrical Characteristics 12.3 DC Characteristics	Revised the minimum value of VIH6 2.0 -> 2.3
52	12. Electrical Characteristics 12.3 DC Characteristics	Revised the following DC characteristics I _{CC5} , I _{CCS5} , I _{CC52} , I _{CH52}
55	12. Electrical Characteristics 12.4.2 Internal Clock Timing	Revised the product names in the table S6J311AHAA-> S6J311xHAA
55	12. Electrical Characteristics 12.4.2 Internal Clock Timing	Delete the line of FCD0_CLK and tCD0_CLK
57	12. Electrical Characteristics 12.4.2 Internal Clock Timing	Revised the note as follow FCD0_CLK->FCPU_CLK
58	12. Electrical Characteristics 12.4.2 Internal Clock Timing	Revised the voltage value of Hysteresis input pin (TTL). 2.0V -> 2.3V
60	12. Electrical Characteristics 12.4.4 Power-on Conditions	Revised the value of Level detection voltage
60	12. Electrical Characteristics 12.4.4 Power-on Conditions	Added the line of Level release voltage